

TSMC-01-144



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To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

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Subject:

Serial No. 10/086,258 03/04/02

Ming-Hwa Yoo, Shih-Chi Lin,
Yi-Lung Cheng, Szu-An Wu,
Ying-Lang Wang

A NOVEL METHOD TO SOLVE IMD-FSG
PARTICLE AND INCREASE Cp YIELD BY
USING A NEW TOUGHER UFUN SEASON FILM

Grp. Art Unit: 1763

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner of Patents and
Trademarks, Washington, D.C. 20231, on May 14, 2002.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 5/14/02

U.S. Patent 5,983,906 to Zhao et al., "Methods and Apparatus for a Cleaning Process in a High Temperature, Corrosive, Plasma Environment," describes systems, methods and apparatus for depositing titanium films at rates of up to 200 Å/minute on semiconductor substrates from a titanium tetrachloride source.

U.S. Patent 6,020,035 to Gupta et al., "Film to Tie Up Loose Fluorine in the Chamber After a Clean Process," describes an undoped silicate glass (USG) seasoning film and process.

U.S. Patent 5,811,356 to Murugesh et al., "Reduction in Mobile Ion and Metal Contamination by Varying Season Time and Bias RF Power During Chamber Cleaning," describes a method and apparatus for reducing the concentration of mobile ion and metal contaminants in a processing chamber.

U.S. Patent 6,121,161 to Rossman et al., "Reduction of Mobile Ion and Metal Contamination in HDP-CVD Chambers Using Chamber Seasoning Film Depositions," describes a method and apparatus for controlling the introduction of contaminates into a deposition chamber that occur naturally within the chamber components.

TSMC-01-144

U.S. Patent 6,136,211 to Qian et al., "Self-Cleaning Etch Process," describes a self-cleaning etch process whereby during etching of a substrate in an etching chamber, a thin non-homogeneous etch residue deposited on the surfaces of the walls and components of the etching chamber are simultaneously cleaned.

U.S. Patent 5,705,080 to Leung et al., "Plasma-Inert Cover and Plasma Cleaning Process," describes a plasma-inert cover and plasma cleaning process.

Sincerely,


Stephen B. Ackerman,
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